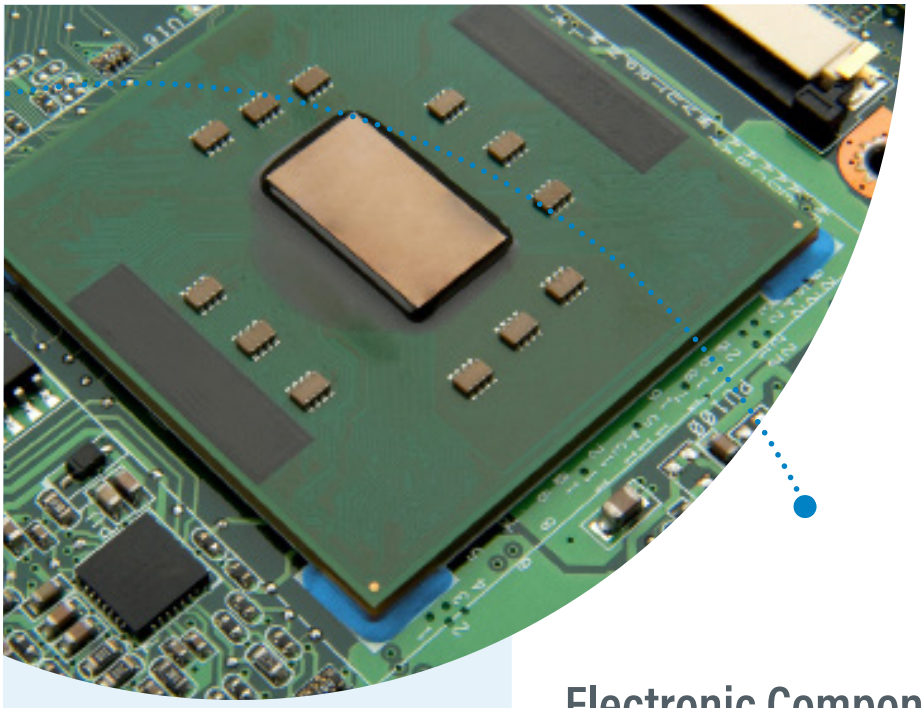


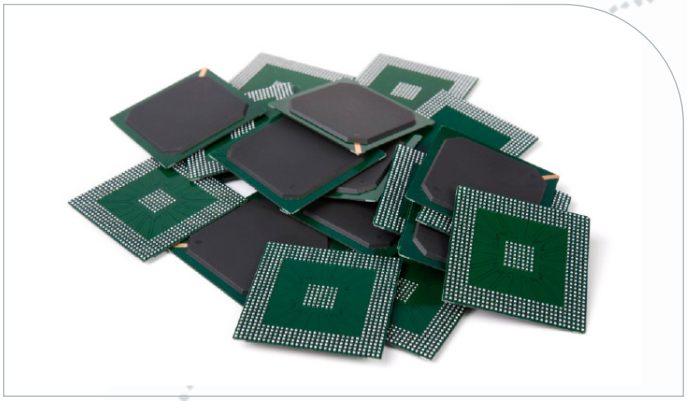
Electronic Component Ruggedization

- Fast, ambient dispense and cure in seconds
- Engineered bead shape for wetting both board surface and component edge without seeping into shadowed area
- Highly thixotropic for zero movement prior to cure
- Low modulus for minimal stress in component interfaces
- Available with See-Cure technology
- Exhibit improved bond strength for die and pry testing
- Halogen and silicone free
- RoHS Compliant
- Easy rework – adhesive leaves no residue on solder pads or between solder balls
- Materials enhance PCB life and reduce stress on interconnects during push, pull, shock, drop, and vibration
- Eliminate leadless component (BGA/VGA) interconnect cracking due to CTE mismatch
- Post reflow application
- Simple visual inspection
- Very low VOCs
- Solvent and HAP free
- No energy required for curing ovens

Various technologies are available for ensuring critical components on printed circuit boards remain intact throughout manufacturing, assembly qualification, and service environment for the duration of product lifecycle. Should one ball-grid interconnect fail, an entire device could be compromised. Dymax has developed the next generation family of edge-bonding adhesives engineered specifically for bonding high-value PCB components. Dymax light-curable adhesives dispense and cure in seconds to provide the optimal balance of production efficiency and technical performance.

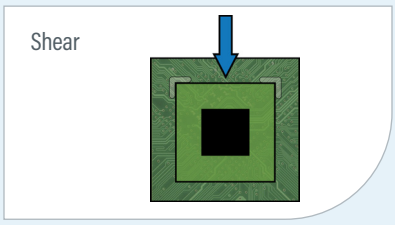
Typical Applications

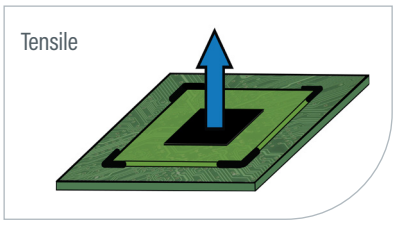
- Handheld electronic devices
- Mobile phones
- Laptop computers
- Gaming consoles
- GPS (global positioning systems)
- Digital music players

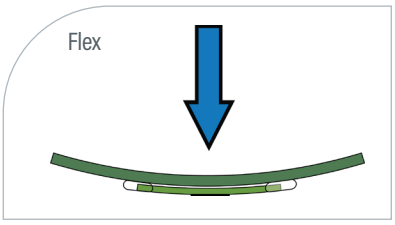


Product	Typical Applications	Features	Viscosity, cP	Cure Data, Approximate Exposure or Belt Speed			Typical Bond Strength, kgf [lbf]		
				BlueWave® 200 UV Curing Spot Lamp* (10 W/cm²)	5000-EC Flood Lamp System (200 mW/cm²)	UVCS Conveyor with Fusion D Lamps (2,500 mW/cm²)	Shear	Tensile	Flex
9422-SC	Edge bonding, component ruggedization, corner bonding	High viscosity/ thixotropy for zero flow after dispense, UV/Visible light cure, See-Cure	38,000	2 sec.	10 sec.	1.8 m/min [6.0 fpm]	16 [35]	8.2 [18]	28 [62]
9309-SC			45,000	4 sec.	20 sec.	2.4 m/min [8.0 fpm]	8 [18]	5.4 [12]	7.8 [17]

* Time to complete the transition from blue to clear at an adhesive thickness of 0.10 mm [4.0 mil]. Cure times based on laboratory conditions.







See-Cure Technology

Dymax adhesives formulated with See-Cure technology have built-in cure validation that makes it easy for operators or simple automated inspection equipment to confirm cure without investing in additional specialized equipment. These materials are bright blue in their uncured state, making them highly visible when dispensed onto substrates. Workers can easily confirm the adhesive placement and quantity with just their eyes.

After the adhesive is exposed to light, the color transitions from blue to colorless. This cure indicator ensures the adhesive is completely cured, providing a critical safety feature for manufacturing processes.

DYMAX®

www.dymax.com

Americas
USA | +1.860.482.1010 | info@dymax.com

Europe
Germany | +49 611.962.7900 | info_de@dymax.com
Ireland | +353 21.237.3016 | info_ie@dymax.com

Asia
Singapore | +65.67522887 | info_ap@dymax.com
China | +86.755.83485759 | dymaxasia@dymax.com
Hong Kong | +852.2460.7038 | dymaxasia@dymax.com
Korea | +82.31.608.3434 | info_kr@dymax.com

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